















ESD

TVS

MOS

LDO

Diode

Sensor

DC-DC

Product Specification

Domestic Part Number	SS12F THRU SS120F
Overseas Part Number	SS12F THRU SS120F
▶ Equivalent Part Number	SS12F THRU SS120F





SMAF Plastic-Encapsulate Diodes

SS12F THRU SS120F Schottky Rectifier Diodes

Features

• I_{F(AV)} 1A

• V_{RRM} 20V-200V

High surge current capability

• Polarity: Color band denotes cathode

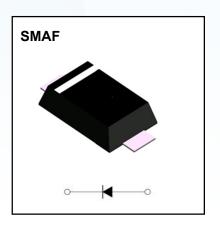
Applications

Rectifier

Marking

• SS1X

X: From 2 To 20



Limiting Values(Absolute Maximum Rating)

	Symbol	Unit		SS1									
Item			Test Conditions		3F	4F	5F	6F	8F	10F	15F	20F	
Repetitive Peak Reverse Voltage	V_{RRM}	V		20	30	40	50	60	80	100	150	200	
Maximum RMS Voltage	V _{RMS}	V		14	21	28	35	42	56	70	105	140	
Average Forward Current	I _{F(AV)}	Α	60Hz Half-sine wave, Resistance load, TL(Fig.1)	1.0									
Surge(Non-repetitive)Forward Current	I _{FSM}	Α	60Hz Half-sine wave, 1 cycle, Ta=25°C	30									
Junction Temperature	TJ	$^{\circ}$		-55~+125 -55~+150			0						
Storage Temperature	T _{STG}	$^{\circ}$		-55 ~ +150									

Electrical Characteristics (T =25°C Unless otherwise specified)

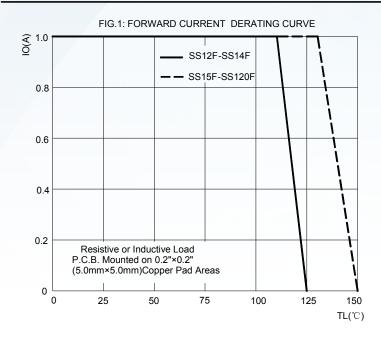
lt a ma	Comple of	11:4	Test Condition		SS1										
Item	Symbol	Unit			2F	3F	4F	5F	6F	8F	10F	15F	20F		
Peak Forward Voltage	V_{F}	\	I _F =		0.55 0.70			0.85 0.95			95				
Dook Doverse Coment	I _{RRM1}	mΛ	\/ -\/	T _a =25°C			0.5			0.1					
Peak Reverse Current	rse Current I _{RRM2} mA		$V_{RM}=V_{RRM}$	T _a =100°C		10		5.0							
Thermal	$R_{\theta J-A}$	℃/	Between junct	tion and ambient				88							
Resistance(Typical)	$R_{\theta J-L}$	W	Between junct	tion and terminal	28										

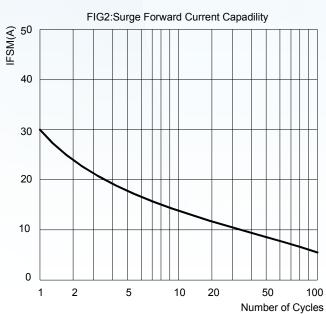
Notes:

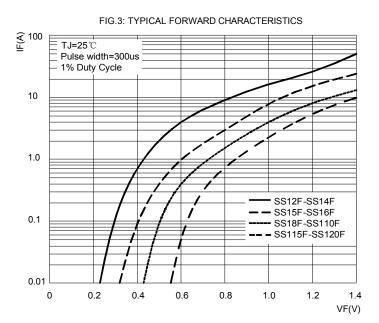
Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.2" x 0.2" (5.0 mm x 5.0 mm) copper pad areas

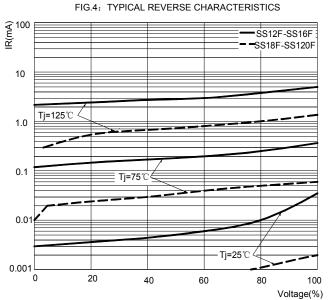


Typical Characteristics



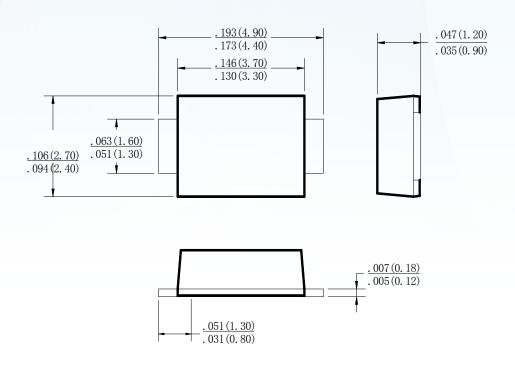






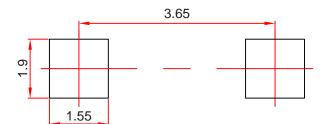


SMAF Package Outline Dimensions



Dimensions in inches and (millimeters)

SMAF Suggested Pad Layout



Note:

- 1. Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

NOTICE

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Reel Taping Specifications For Surface Mount Devices-SMAF

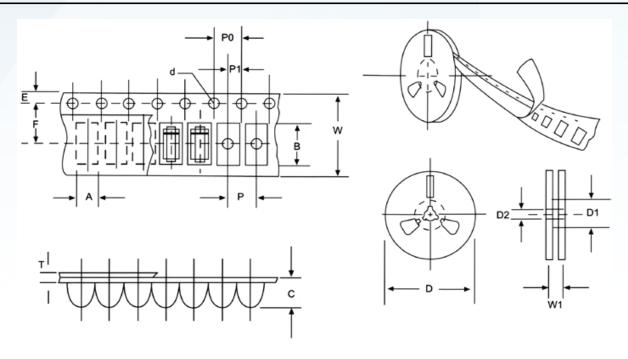


FIG: CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING

ITEM	SYMBOL	SMAF mm(inch)
Carrier width	A	2.83+0.1(0.112+0.004)
Carrier length	В	4.90+0.1(0.193+0.004)
Carrier depth	С	1.45+0.1(0.057+0.004)
Sprocket hole	d	1.55+0.05(0.061+0.002)
Reel outside diameter	D	178+2.0(7.0+0.079)
Reel inner diameter	D1	54±1.0(2.13±0.039)
Feed hole diameter	D2	13+0.5(0.512+0.020)
Strocket hole position	E	1.75+0.1(0.069+0.004)
Punch hole position	F	5.5+0.05(0.217+0.002)
Punch hole pitch	Р	4.0+0.1(0.157+0.004)
Sprocket hole pitch	P0	4.0+0.1(0.157+0.004)
Embossment center	P1	2.0+0.1(0.079+0.004)
Totall tape thickness	Т	0.23-0.29(0.009-0.011)
Tape width	W	12.0+0.1(0.472+0.004)
Reel width	W1	16.8+2.0(0.661+0.079)

NOTE:Devices are packde in accordance with EIA standard RS-481-A and specification given above.



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